

Listing of the Claims

1. (original) A method of cleaning a wafer, comprising the steps of:

providing a surfactant composition solution;
subjecting said wafer to a plurality of polishing steps;
applying said surfactant composition solution to said wafer after at least one of said plurality of polishing steps; and
rinsing said wafer.

2. (original) The method of claim 1 wherein said applying said surfactant composition to said wafer comprises applying said surfactant composition to said wafer after completion of said plurality of polishing steps.

3. (original) The method of claim 1 wherein said surfactant solution comprises an aqueous alcohol solution.

4. (original) The method of claim 3 wherein said applying said surfactant composition to said wafer comprises applying said surfactant composition to said wafer after completion of said plurality of polishing steps.

5. (original) The method of claim 1 wherein said rinsing said wafer comprises providing deionized water and rinsing said wafer using said deionized water.

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6. (original) The method of claim 5 wherein said applying said surfactant composition to said wafer comprises applying said surfactant composition to said wafer after completion of said plurality of polishing steps.

7. (original) The method of claim 5 wherein said surfactant solution comprises an aqueous alcohol solution.

8. (original) The method of claim 3 wherein said aqueous alcohol solution comprises from about 0.01% to about 1% alcohol by volume.

9. (original) The method of claim 8 wherein said applying said surfactant composition to said wafer comprises applying said surfactant composition to said wafer after completion of said plurality of polishing steps.

10. (original) The method of claim 8 wherein said rinsing said wafer comprises providing deionized water and rinsing said wafer using said deionized water.

11. (original) The method of claim 8 wherein said alcohol comprises octanol.

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12. (original) The method of claim 8 further comprising ethylene oxide in said aqueous alcohol solution.

13. (original) A method of cleaning a wafer, comprising the steps of:

providing a surfactant composition solution;

subjecting said wafer to a plurality of polishing steps;

applying said surfactant composition solution to said wafer after each of said plurality of polishing steps; and

rinsing said wafer.

14. (original) The method of claim 13 wherein said surfactant solution comprises an aqueous alcohol solution.

15. (original) The method of claim 14 wherein said aqueous alcohol solution comprises from about 0.01% to about 1% alcohol by volume.

16. (original) The method of claim 15 further comprising ethylene oxide in said aqueous alcohol solution.

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17. (withdrawn) A composition solution for rendering a surface on a wafer hydrophilic to facilitate rinsing of the wafer with water, comprising:

an aqueous solution comprising less than about 1% alcohol.

18. (withdrawn) The composition solution of claim 17 wherein said alcohol is an alcohol having the formula $C_nH_{2n-1}OH$, where n is any one of the integers 4-12.

19. (withdrawn) The composition solution of claim 17 wherein said alcohol is octanol.

20. (withdrawn) The composition solution of claim 17 wherein said aqueous alcohol solution comprises from about 0.01% to about 1% alcohol by volume and ethylene oxide.